

APPENDIX D

Z (AXIAL) MEASUREMENT: CDMA 800 Channel 1013

Equipment Setting:

DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;

Date: 10/08/2008

Communication System: CDMA; Frequency: 824.7 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

Scans CH1013/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):

Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = -6.05023 dB A/m

BWC Factor = -0.193996 dB

Location: 5, -2, 363.7 mm

Scans CH1013/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 = -5.23145 dB A/m

BWC Factor = -0.193996 dB

Location: 4.6, -1.8, 363.7 mm

Point meas,TCoil on CH1013/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):

Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM1 comp = -6.88674 dB A/m

BWC Factor = -0.193996 dB

Location: 9, -1, 363.7 mm

Point meas,TCoil on CH1013/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):

Measurement grid: dx=10mm, dy=10mm

Cursor:

ABM2 = -39.267 dB A/m

Location: 9, -1, 363.7 mm

Point meas,TCoil on CH1013/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):

Measurement grid: dx=10mm, dy=10mm

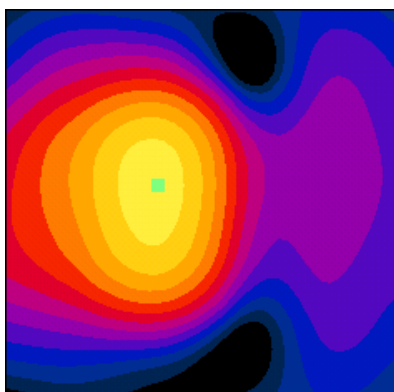
Cursor:

ABM1/ABM2 = 32.3802 dB

BWC Factor = -0.193996 dB

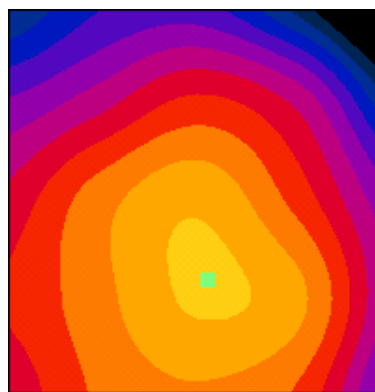
Location: 9, -1, 363.7 mm

Z (axial) rough 50x50 scan:



0 dB = 1.00A/m

Z (axial) 16x16scan:



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 800 Channel 1013**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 824.7 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1013/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -10.6072 dB A/m

BWC Factor = -0.193996 dB

Location: -2.2, -1, 363.7 mm

**Point meas,TCoil on CH1013/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -11.6385 dB A/m

BWC Factor = -0.193996 dB

Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH1013/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -27.2014 dB A/m

Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH1013/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

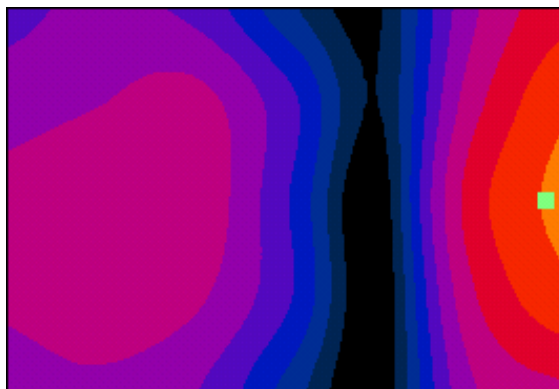
**Cursor:**

ABM1/ABM2 = 15.5629 dB

BWC Factor = -0.193996 dB

Location: -3, -1, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 800 Channel 1013**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 824.7 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1013/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.863 dB A/m

BWC Factor = -0.193996 dB

Location: 5, 9, 363.7 mm

**Point meas, TCoil on CH1013/y (transversal) at max**

**y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -16.8435 dB A/m

BWC Factor = -0.193996 dB

Location: 1, -5, 363.7 mm

**Point meas, TCoil on CH1013/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -43.5049 dB A/m

Location: 1, -5, 363.7 mm

**Point meas, TCoil on CH1013/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

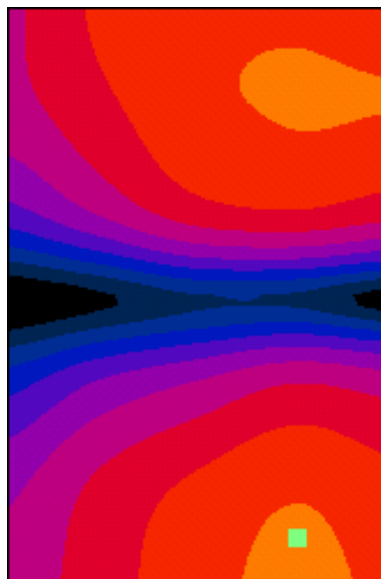
**Cursor:**

ABM1/ABM2 = 26.6614 dB

BWC Factor = -0.193996 dB

Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 800 Channel 383**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**  
 Communication System: CDMA; Frequency: 836.49 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 10/08/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH383/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.11536 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 5, -3, 363.7 mm

**Scans CH383/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.50236 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 5.4, -3, 363.7 mm

**Point meas, TCoil on CH383/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -6.98781 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 9, -1, 363.7 mm

**Point meas, TCoil on CH383/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -38.6169 dB A/m  
 Location: 9, -1, 363.7 mm

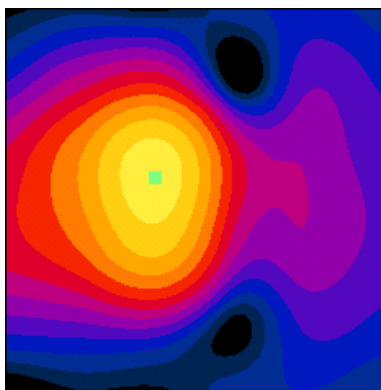
**Point meas, TCoil on CH383/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

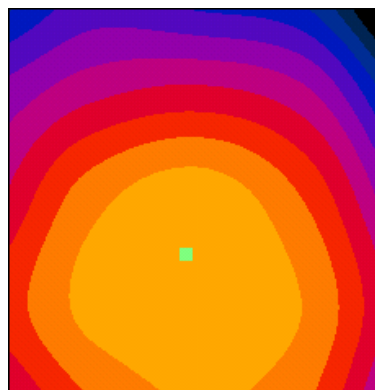
ABM1/ABM2 = 31.6291 dB  
 BWC Factor = -0.193996 dB  
 Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16 scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 800 Channel 383**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**  
 Communication System: CDMA; Frequency: 836.49 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 10/08/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH383/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -10.5907 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: -3, -3.4, 363.7 mm

**Point meas,TCoil on CH383/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -10.8159 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH383/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -26.9026 dB A/m  
 Location: -3, -5, 363.7 mm

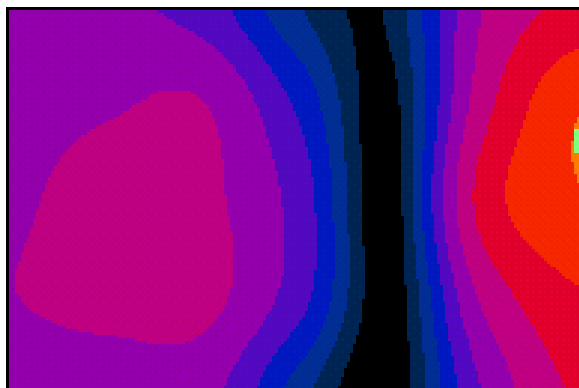
**Point meas,TCoil on CH383/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 16.0867 dB  
 BWC Factor = -0.193996 dB  
 Location: -3, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 800 Channel 383**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**  
 Communication System: CDMA; Frequency: 836.49 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 10/08/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH383/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.8223 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 3.8, -9.4, 363.7 mm

**Point meas,TCoil on CH383/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -17.5593 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH383/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -42.7907 dB A/m  
 Location: 1, -5, 363.7 mm

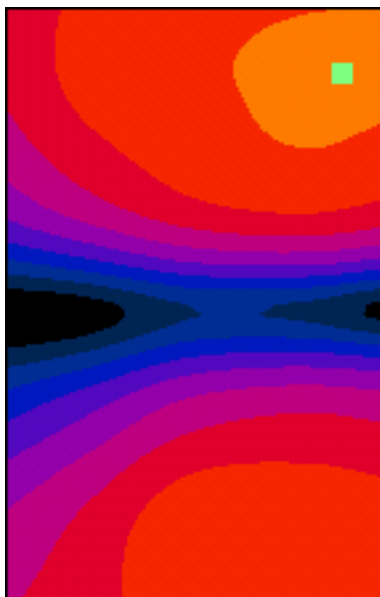
**Point meas,TCoil on CH383/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 25.2314 dB  
 BWC Factor = -0.193996 dB  
 Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 800 Channel 777**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**  
 Communication System: CDMA; Frequency: 848.31 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 10/08/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH777/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.75807 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 5, -3, 363.7 mm

**Scans CH777/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.44758 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 4.2, -1, 363.7 mm

**Point meas,TCoil on CH777/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -6.66365 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH777/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -39.4574 dB A/m  
 Location: 9, -1, 363.7 mm

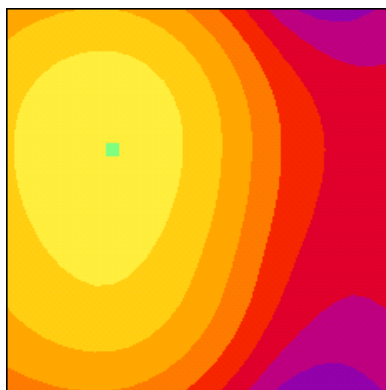
**Point meas,TCoil on CH777/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

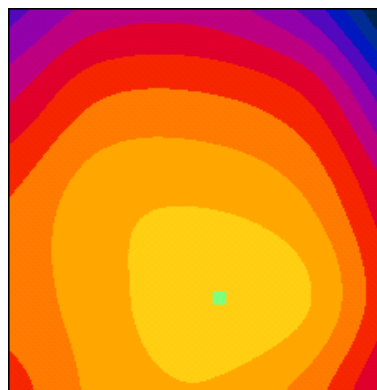
ABM1/ABM2 = 32.7937 dB  
 BWC Factor = -0.193996 dB  
 Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 800 Channel 777**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**  
 Communication System: CDMA; Frequency: 848.31 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 10/08/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH777/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -10.7624 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: -3, -4.6, 363.7 mm

**Point meas,TCoil on CH777/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -11.0309 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH777/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -27.9666 dB A/m  
 Location: -3, -5, 363.7 mm

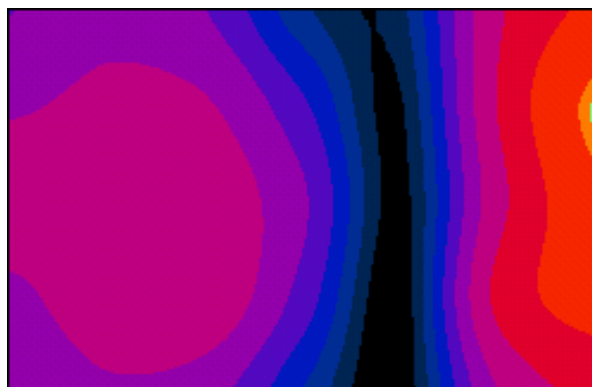
**Point meas,TCoil on CH777/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 16.9357 dB  
 BWC Factor = -0.193996 dB  
 Location: -3, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m



**Y RADIAL MEASUREMENT: CDMA 800 Channel 777**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**  
 Communication System: CDMA; Frequency: 848.31 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**Date: 10/08/2008**

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH777/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.1005 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 5, -9.4, 363.7 mm

**Point meas,TCoil on CH777/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -17.5959 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH777/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -43.9422 dB A/m  
 Location: 1, -5, 363.7 mm

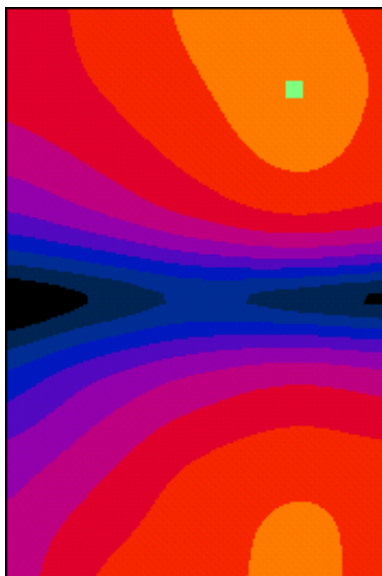
**Point meas,TCoil on CH777/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 26.3463 dB  
 BWC Factor = -0.193996 dB  
 Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 1700 Channel 25**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1711.25 MHz; Duty Cycle: 1:2.61

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008

- Sensor-Surface: 0mm (Fix Surface)

- Electronics: DAE4 Sn530; Calibrated: 4/15/2008

- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x

- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -7.03782 dB A/m

BWC Factor = -0.196003 dB

Location: 5, -1, 363.7 mm

**Scans CH25/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.04145 dB A/m

BWC Factor = -0.196003 dB

Location: 3, -0.6, 363.7 mm

**Point meas,TCoil on CH25/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -43.8779 dB A/m

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH25/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -8.04935 dB A/m

BWC Factor = -0.196003 dB

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH25/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

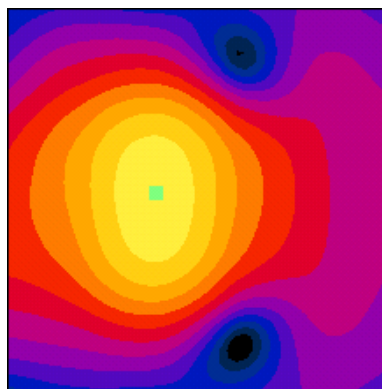
**Cursor:**

ABM1/ABM2 = 35.8285 dB

BWC Factor = -0.196003 dB

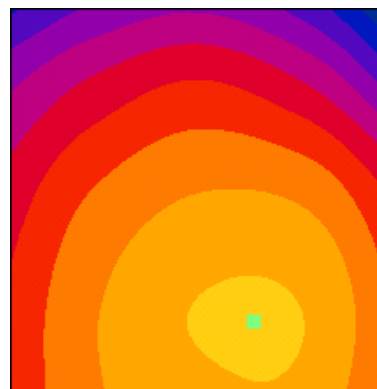
Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1700 Channel 25**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1711.25 MHz; Duty Cycle: 1:2.61  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/x (longitudinal) 24 x 16/ABM**

**Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -11.7139 dB A/m  
 BWC Factor = -0.196003 dB  
 Location: -1.8, -1.4, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**

**x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -10.2898 dB A/m  
 BWC Factor = -0.196003 dB  
 Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**

**x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -28.7142 dB A/m  
 Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**

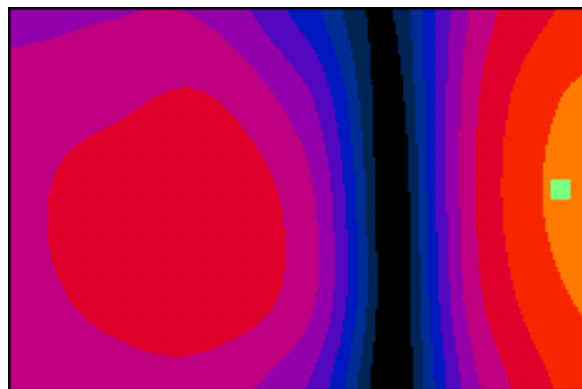
**x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 18.4243 dB  
 BWC Factor = -0.196003 dB  
 Location: -3, -1, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1700 Channel 25**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1711.25 MHz; Duty Cycle: 1:2.61  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.0719 dB A/m  
 BWC Factor = -0.196003 dB  
 Location: 4.6, -9.4, 363.7 mm

**Point meas,TCoil on CH25/y (transversal) at max**

**y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -16.1082 dB A/m  
 BWC Factor = -0.196003 dB  
 Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH25/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -43.8148 dB A/m  
 Location: 1, -5, 363.7 mm

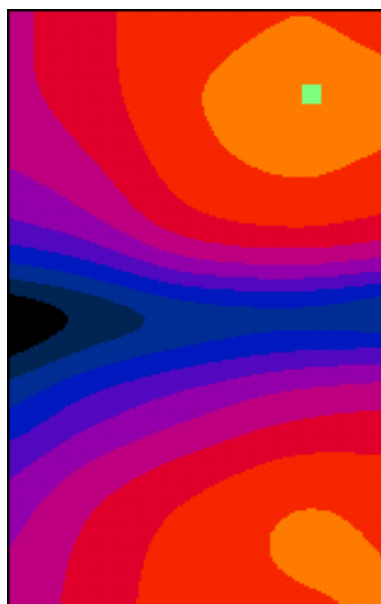
**Point meas,TCoil on CH25/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 27.7066 dB  
 BWC Factor = -0.196003 dB  
 Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 1700 Channel 450**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1732.5 MHz; Duty Cycle: 1:2.61

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH450/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.29217 dB A/m

BWC Factor = -0.196003 dB

Location: 5, -1, 363.7 mm

**Scans CH450/z (axial) 16 x 16/ABM Interpolated**

**Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.57264 dB A/m

BWC Factor = -0.196003 dB

Location: 4.6, -0.6, 363.7 mm

**Point meas,TCoil on CH450/z (axial) at max z/ABM**

**Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -7.69035 dB A/m

BWC Factor = -0.196003 dB

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH450/z (axial) at max z/ABM**

**Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -44.2235 dB A/m

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH450/z (axial) at max z/ABM**

**SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

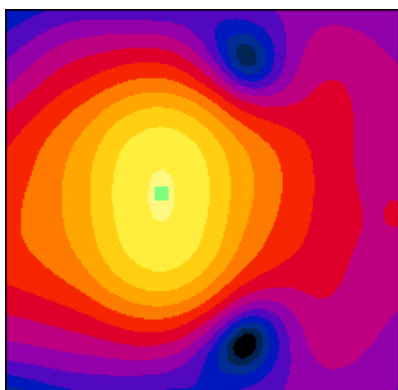
**Cursor:**

ABM1/ABM2 = 36.5332 dB

BWC Factor = -0.196003 dB

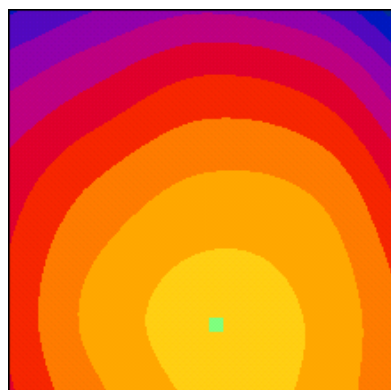
Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1700 Channel 450**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1732.5 MHz; Duty Cycle: 1:2.61

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH450/x (longitudinal) 24 x 16/ABM**

**Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -11.0883 dB A/m

BWC Factor = -0.196003 dB

Location: -2.2, -1, 363.7 mm

**Point meas,TCoil on CH450/x (longitudinal) at max**

**x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -10.777 dB A/m

BWC Factor = -0.196003 dB

Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH450/x (longitudinal) at max**

**x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -29.3208 dB A/m

Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH450/x (longitudinal) at max**

**x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

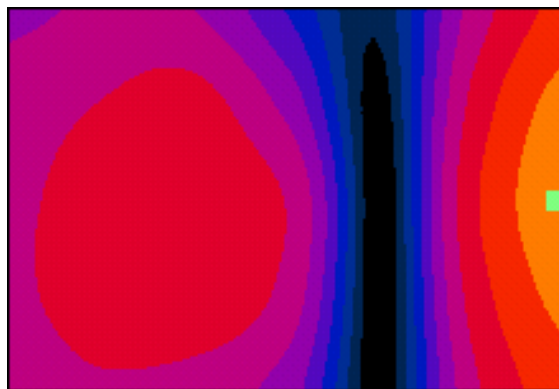
**Cursor:**

ABM1/ABM2 = 18.5437 dB

BWC Factor = -0.196003 dB

Location: -3, -1, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1700 Channel 450**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1732.5 MHz; Duty Cycle: 1:2.61

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH450/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -12.9923 dB A/m

BWC Factor = -0.196003 dB

Location: 4.6, -9.8, 363.7 mm

**Point meas,TCoil on CH450/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -15.3923 dB A/m

BWC Factor = -0.196003 dB

Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH450/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -44.3039 dB A/m

Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH450/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

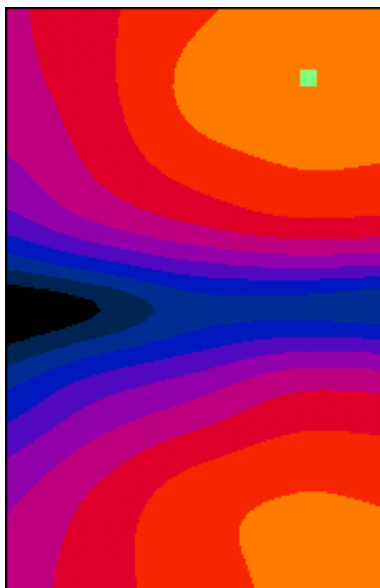
**Cursor:**

ABM1/ABM2 = 28.9116 dB

BWC Factor = -0.196003 dB

Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 1700 Channel 875**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1753.75 MHz; Duty Cycle: 1:2.61

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH875/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.83575 dB A/m  
 BWC Factor = -0.196003 dB  
 Location: 5, -2, 363.7 mm

**Scans CH875/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.5817 dB A/m  
 BWC Factor = -0.196003 dB  
 Location: 2.6, -0.6, 363.7 mm

**Point meas, TCoil on CH875/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -7.52842 dB A/m  
 BWC Factor = -0.196003 dB  
 Location: 9, -1, 363.7 mm

**Point meas, TCoil on CH875/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -44.2876 dB A/m  
 Location: 9, -1, 363.7 mm

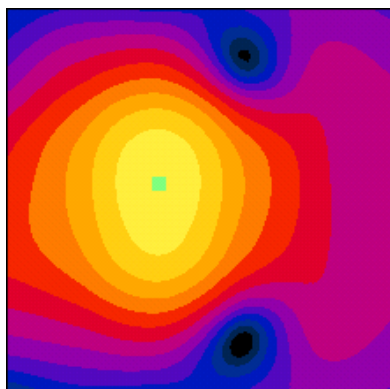
**Point meas, TCoil on CH875/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

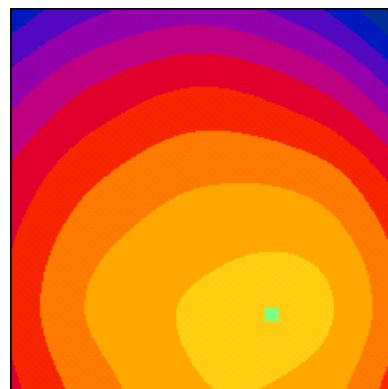
ABM1/ABM2 = 36.7592 dB  
 BWC Factor = -0.196003 dB  
 Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16scan:**



0 dB = 1.00A/m



**X RADIAL MEASUREMENT: CDMA 1700 Channel 875**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1753.75 MHz; Duty Cycle: 1:2.61

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH875/x (longitudinal) 24 x 16/ABM**

**Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -11.435 dB A/m

BWC Factor = -0.196003 dB

Location: -1.8, -1.8, 363.7 mm

**Point meas,TCoil on CH875/x (longitudinal) at max**

**x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -11.4971 dB A/m

BWC Factor = -0.196003 dB

Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH875/x (longitudinal) at max**

**x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -29.3453 dB A/m

Location: -3, -5, 363.7 mm

**Point meas,TCoil on CH875/x (longitudinal) at max**

**x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

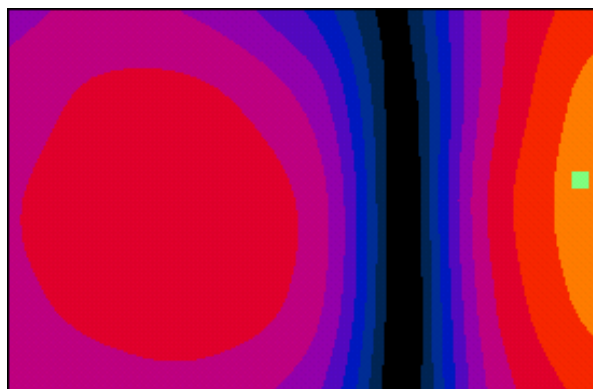
**Cursor:**

ABM1/ABM2 = 17.8482 dB

BWC Factor = -0.196003 dB

Location: -3, -5, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1700 Channel 875**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/14/2008**

Communication System: AWS-1700; Frequency: 1753.75 MHz; Duty Cycle: 1:2.61

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH875/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -12.3336 dB A/m

BWC Factor = -0.196003 dB

Location: 5, -9.4, 363.7 mm

**Point meas,TCoil on CH875/y (transversal) at max**

**y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -15.4224 dB A/m

BWC Factor = -0.196003 dB

Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH875/y (transversal) at max**  
**y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -44.083 dB A/m

Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH875/y (transversal) at max**  
**y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

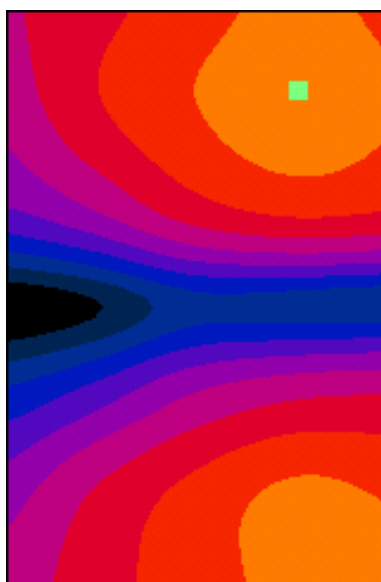
**Cursor:**

ABM1/ABM2 = 28.6606 dB

BWC Factor = -0.196003 dB

Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 25**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 1850 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.2534 dB A/m

BWC Factor = -0.193996 dB

Location: 5, -2, 363.7 mm

**Scans CH25/z (axial) 16 x 16/ABM Interpolated**

**Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.37386 dB A/m

BWC Factor = -0.193996 dB

Location: 2.6, -1, 363.7 mm

**Point meas,TCoil on CH25/z (axial) at max z/ABM**

**Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -6.62795 dB A/m

BWC Factor = -0.193996 dB

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH25/z (axial) at max z/ABM**

**Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -39.6232 dB A/m

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH25/z (axial) at max z/ABM**

**SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

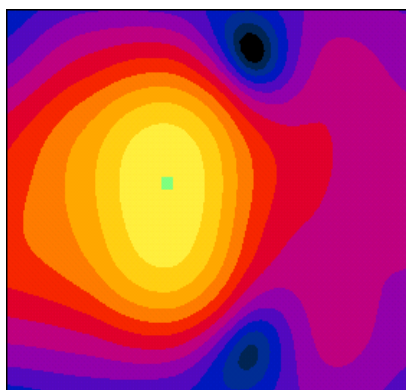
ABM1/ABM2 = 32.9952 dB

BWC Factor = -0.193996 dB

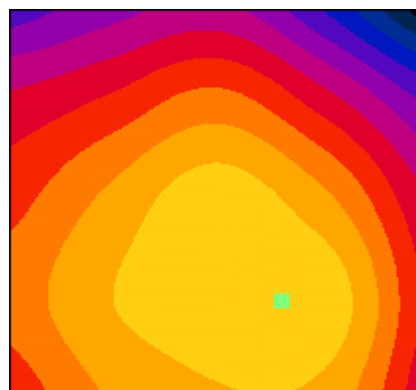
Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**

**Z (axial) 16x16scan:**



0 dB = 1.00A/m



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1900 Channel 25**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 1850 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/x (longitudinal) 24 x 16/ABM**

**Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -10.6747 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: -2.2, -1, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**

**x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -11.2278 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**

**x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -26.903 dB A/m  
 Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH25/x (longitudinal) at max**

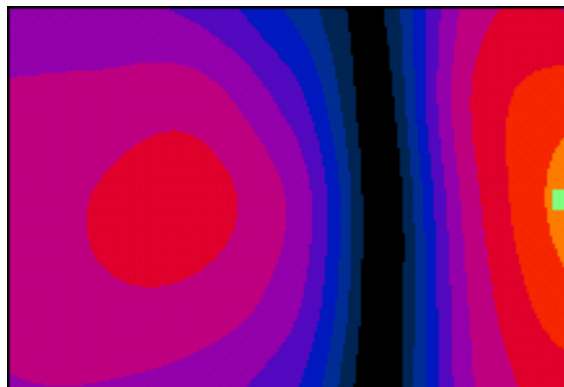
**x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 15.6752 dB  
 BWC Factor = -0.193996 dB  
 Location: -3, -1, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1900 Channel 25**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 1850 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH25/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.3764 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 5, -9.4, 363.7 mm

**Point meas,TCoil on CH25/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -17.2154 dB A/m  
 BWC Factor = -0.193996 dB  
 Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH25/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -42.7554 dB A/m  
 Location: 1, -5, 363.7 mm

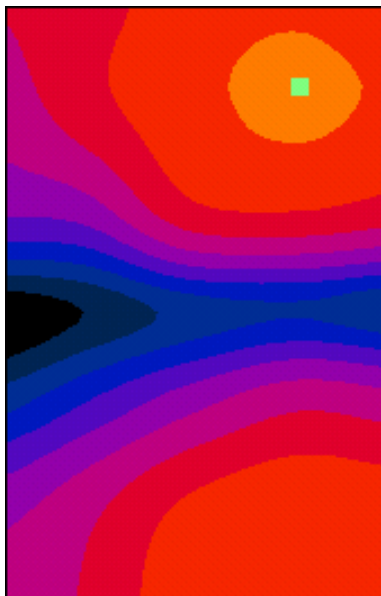
**Point meas,TCoil on CH25/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 25.5401 dB  
 BWC Factor = -0.193996 dB  
 Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m

**Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 600**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008

- Sensor-Surface: 0mm (Fix Surface)

- Electronics: DAE4 Sn530; Calibrated: 4/15/2008

- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x

- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH600/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -6.60954 dB A/m

BWC Factor = -0.193996 dB

Location: 5, -3, 363.7 mm

**Scans CH600/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -4.7431 dB A/m

BWC Factor = -0.193996 dB

Location: 5, -1, 363.7 mm

**Point meas,TCoil on CH600/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

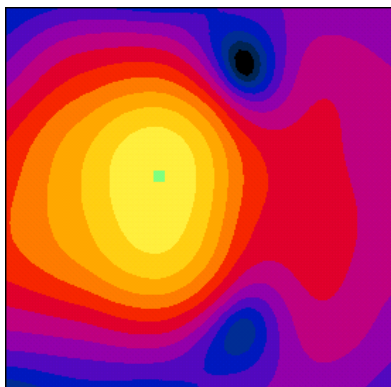
Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -39.8184 dB A/m

Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Point meas,TCoil on CH600/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -6.66919 dB A/m

BWC Factor = -0.193996 dB

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH600/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

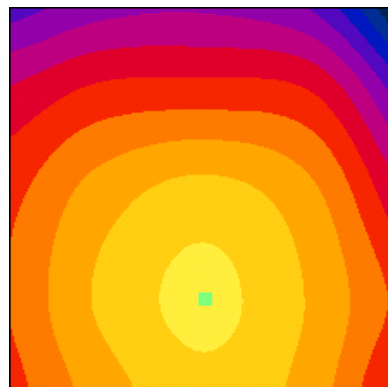
**Cursor:**

ABM1/ABM2 = 33.1492 dB

BWC Factor = -0.193996 dB

Location: 9, -1, 363.7 mm

**Z (axial) 16x16scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1900 Channel 600**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH600/x (longitudinal) 24 x 16/ABM**

**Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -10.9826 dB A/m

BWC Factor = -0.193996 dB

Location: -2.2, -0.6, 363.7 mm

**Point meas,TCoil on CH600/x (longitudinal) at max**

**x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -27.9434 dB A/m

Location: -3, -1, 363.7 mm

**X (Radial) 24x16 scan:**

**Point meas,TCoil on CH600/x (longitudinal) at max**

**x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -10.3832 dB A/m

BWC Factor = -0.193996 dB

Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH600/x (longitudinal) at max**

**x/ABM SNR(x,y,z) (1x1x1):**

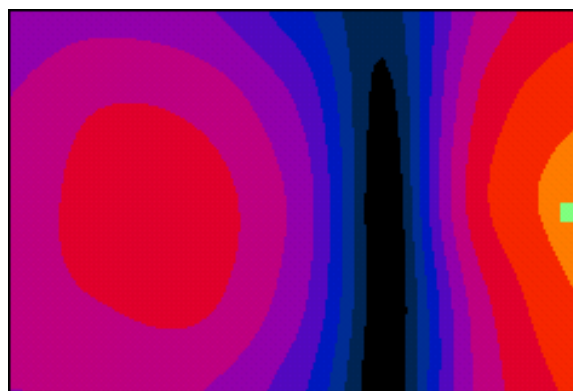
Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1/ABM2 = 17.5601 dB

BWC Factor = -0.193996 dB

Location: -3, -1, 363.7 mm



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1900 Channel 600**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634;**

**Date: 10/08/2008**

Communication System: CDMA; Frequency: 1880 MHz; Duty Cycle: 1:1  
 Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>  
 Phantom section: AMB with Coil Section

**DASY4 Configuration:**

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH600/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.0885 dB A/m

BWC Factor = -0.193996 dB

Location: 5, -9, 363.7 mm

**Point meas,TCoil on CH600/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -16.1943 dB A/m

BWC Factor = -0.193996 dB

Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH600/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -42.9681 dB A/m

Location: 1, -5, 363.7 mm

**Point meas,TCoil on CH600/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

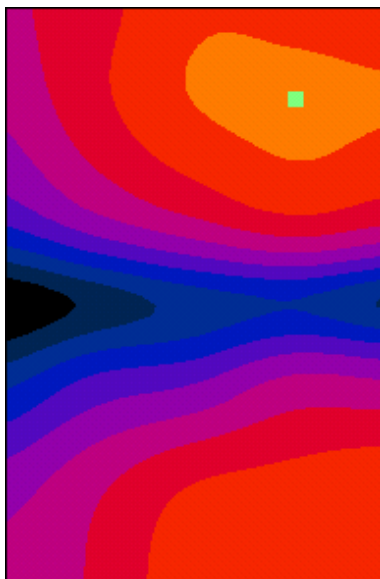
**Cursor:**

ABM1/ABM2 = 26.7738 dB

BWC Factor = -0.193996 dB

Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m



**Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 1175**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634; Date: 10/08/2008**

Communication System: CDMA; Frequency: 1910 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1175/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -7.30706 dB A/m

BWC Factor = -0.204999 dB

Location: 5, -1, 363.7 mm

**Scans CH1175/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -5.91187 dB A/m

BWC Factor = -0.204999 dB

Location: 4.2, -1, 363.7 mm

**Point meas,TCoil on CH1175/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -8.25658 dB A/m

BWC Factor = -0.207 dB

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH1175/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -39.7184 dB A/m

Location: 9, -1, 363.7 mm

**Point meas,TCoil on CH1175/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

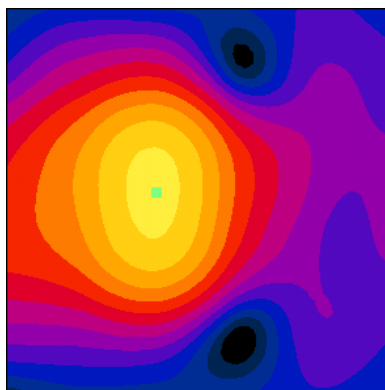
**Cursor:**

ABM1/ABM2 = 31.4619 dB

BWC Factor = -0.207 dB

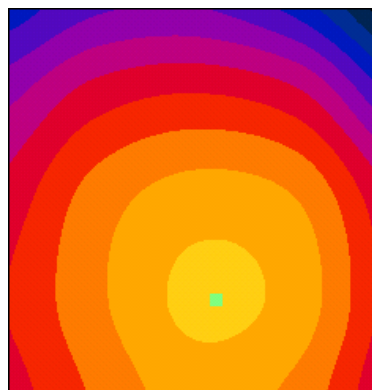
Location: 9, -1, 363.7 mm

**Z (axial) rough 50x50 scan:**



0 dB = 1.00A/m

**Z (axial) 16x16scan:**



0 dB = 1.00A/m

**X RADIAL MEASUREMENT: CDMA 1900 Channel 1175**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634; Date: 10/08/2008**

Communication System: CDMA; Frequency: 1910 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1175/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -11.8166 dB A/m

BWC Factor = -0.204999 dB

Location: -2.2, -1, 363.7 mm

**Point meas,TCoil on CH1175/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -11.203 dB A/m

BWC Factor = -0.207 dB

Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH1175/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -25.5537 dB A/m

Location: -3, -1, 363.7 mm

**Point meas,TCoil on CH1175/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

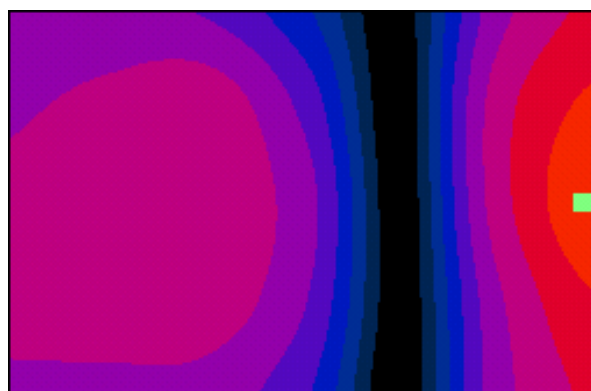
**Cursor:**

ABM1/ABM2 = 14.3507 dB

BWC Factor = -0.207 dB

Location: -3, -1, 363.7 mm

**X (Radial) 24x16 scan:**



0 dB = 1.00A/m

**Y RADIAL MEASUREMENT: CDMA 1900 Channel 1175**

**Equipment Setting:**

**DUT: Ceramix; Type: Cellular Phone ; Serial Number: #1634; Date: 10/08/2008**

Communication System: CDMA; Frequency: 1910 MHz; Duty Cycle: 1:1

Medium parameters used:  $\sigma = 0$  mho/m,  $\epsilon_r = 1$ ;  $\rho = 0$  kg/m<sup>3</sup>

Phantom section: AMB with Coil Section

DASY4 Configuration:

- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 44; Postprocessing SW: SEMCAD, V1.8 Build 171

**Scans CH1175/y (transversal) 16 x 24/ABM**

**Interpolated Signal(x,y,z) (41x61x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 = -13.214 dB A/m

BWC Factor = -0.204999 dB

Location: 5, -9.4, 363.7 mm

**Point meas, TCoil on CH1175/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM1 comp = -17.0535 dB A/m

BWC Factor = -0.207 dB

Location: 1, -5, 363.7 mm

**Point meas, TCoil on CH1175/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

**Cursor:**

ABM2 = -41.4535 dB A/m

Location: 1, -5, 363.7 mm

**Point meas, TCoil on CH1175/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):**

Measurement grid: dx=10mm, dy=10mm

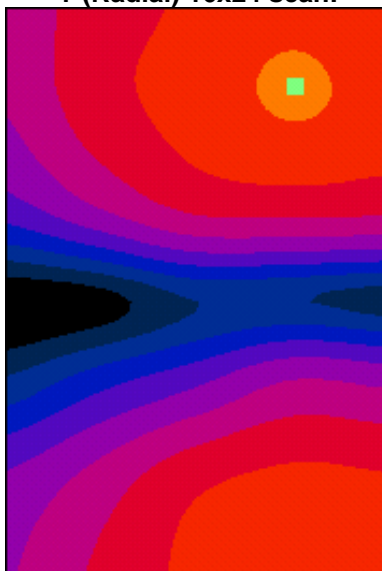
**Cursor:**

ABM1/ABM2 = 24.4 dB

BWC Factor = -0.207 dB

Location: 1, -5, 363.7 mm

**Y (Radial) 16x24 scan:**



0 dB = 1.00A/m